

INERTIAL 2020

The 7th IEEE International Symposium on Inertial Sensors & Systems

Grand Prince Hotel Hiroshima | Hiroshima, Japan | March 23-26, 2020



CALL FOR PAPERS

IMPORTANT DATES

October 22, 2019

Abstract Submission

December 8, 2019

Acceptance Notification

January 5, 2020

Late News Submission

January 15, 2020

Late News Acceptance Notification

February 1, 2020

Full Paper Submission Deadline

February 1, 2020

Early Registration Deadline

ORGANIZERS

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This exclusive international Symposium on Inertial Sensors and Systems will be held in Hiroshima, Japan. The event continues our annual tradition of informal single-track international meetings discussing the latest developments in the area of modern inertial sensors and emerging applications. The INERTIAL 2020 will be a four-day event with one day of tutorials, and three days of technical sessions.

INERTIAL 2020 will be held at the Grand Prince Hotel Hiroshima. The hotel stands directly by the beautiful Seto Inland Sea, a 40 minute train ride from Hiroshima Station. Hiroshima Prefecture is located in the southwestern part of the Japanese islands. It is rich in the natural beauty of the Inland Sea and the Chugoku Mountains, with mountains, sea, rivers, valleys, plains, basins that characterize Japan's landscape.

TOPICS OF INTEREST

Sensors Phenomena & Modeling

Theory, new physical principles, device-and-system-level modeling, multi-physics, deterministic/stochastic error models, predictive models

Sensor Systems & Electronics

Sensor arrays, multi-sensor units, inertial measurement units, sensor electronics, actuator systems, control of sensors

Atomic/Quantum Sensors

Theory, new physical principles, device-and-system-level modeling, multi-physics, deterministic/stochastic error models, predictive models

Low-cost Manufacturing

Wafer-level fabrication, new micro/nano techniques, new materials, built-in diagnostics

Advanced Packaging

Wafer-level, system-in-package, vacuum/differential packaging

Advanced Test & Evaluation

Low-cost test/evaluation, calibration of arrays, wafer-level test and evaluation

Aiding Technology

Hybrid systems, gravitational maps, star-trackers, vision

Emerging Applications

Consumer electronics, medical devices, sport and fitness, automotive, oil/gas exploration, military, aeronautical and space sensor systems

Best Failed Ideas

Once exciting ideas for sensors, systems, components, supporting subsystems, or methods that in the end proved unsuccessful for practical or fundamental reasons